IN THE SPECIFICATION

Page 1, in the first line after the heading CROSS REFERENCE TO RELATED APPLICATION please amend the following paragraph:

This is a continuation-in-part under 35 USC Section 120 of United States patent application serial number 10/060,117 to Wittebrood et al., filed January 31, 2002 ~~(now pending)~~ , now U.S. Patent No. 6,769,484 B2.

Page 6, paragraph [0025]

The aqueous plating bath may include a pyrophosphate as a complexing agent in a range of 0.2 to 2 M/l. For example, the aqueous plating bath may include at least one member of the group consisting of sodium pyrophosphate and potassium pyrophosphate in the range of 0.2 to 2 M/l as a complexing agent. The plating bath preferably comprises sodium pyrophosphate ($Na_4P_2O_7$) or potassium pyrophosphate ($K_4P_2O_7$) as a complexing agent for the metal ions in the bath. The pyrophosphate should be added in the range of 65 to 650 g/l, and preferably 100 to 350 g/l.

Page 7, paragraph [0031] bridging pages 7 and 8,

In an embodiment, taken together the aluminum base substrate and all layers exterior thereto form a metal filler for a brazing operation and have a composition comprising at least, by weight percent:

Si in the range of 5 to 14 %, for example 5 to 12%,

Ni in the range of 0.03 to 8%,

Sn in the range of 0.01 to 7%,

Bi in the range of at most 0.3%,

Sb in the range of at most 0.3%,

Zn in the range of at most 0.3%,

Mg in the range of at most 5%,

balance aluminum and inevitable impurities,

and with the proviso that the mol-ratio of Ni:Sn is in the range of 10:(0.5 to 9), and preferably in the range of 10:(0.5 to 6). The reasons for the limitations of the Ni:Sn mol-ratio have been set out above.